

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An electronic device connecting method comprising:
mounting an electrode of an electronic device closely on a sheet-like porous member having pores, the porous member having a photosensitive layer formed on an inner surface of pores, the photosensitive layer producing or eliminating an ion exchange group by irradiation with energy beams on the inner surface of the pores;

selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams thereby exposing the photosensitive layer to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode;

after said selectively irradiating, filling pores in the latent image of the porous member with a conductive material to simultaneously form a conductive wiring portion and a via contact connected to the electrode; and

bonding the porous member, in which the ~~conductive wiring portion and the via contact~~ are is-formed by said filling, to the electronic device.

Claim 2 (Original): An electronic device connecting method as set forth in claim 1, wherein the mounting comprises pressure sensitive adhesion.

Claim 3 (Currently Amended): An electronic device connecting method as set forth in claim 1, wherein

the photosensitive layer produces or eliminates an ion exchange group in an irradiated or non-irradiated portion of the photosensitive layer of the porous member to form a pattern of an ion exchange group by the energy beams, and

the ~~conductive wiring portion and the via contact are~~ is-formed by selectively absorbing a conductive material or its precursor onto the pattern of the ion exchange group which is formed in the irradiated or non-irradiated portion of the photosensitive layer.

Claim 4 (Original): An electronic device connecting method as set forth in claim 3, further comprising;

electroless plating by using the conductive material or its precursor as a plating nucleus.

Claim 5 (Currently Amended): An electronic device connecting method as set forth in claim 1, wherein the ~~conductive wiring portion and the via contact comprise~~ comprises a region which passes through the porous member, and a region which does not pass through the porous member.

Claim 6 (Original): An electronic device connecting method as set forth in claim 1, wherein the bonding comprises curing after a curing resin impregnates the porous member.

Claims 7-22 (Canceled).